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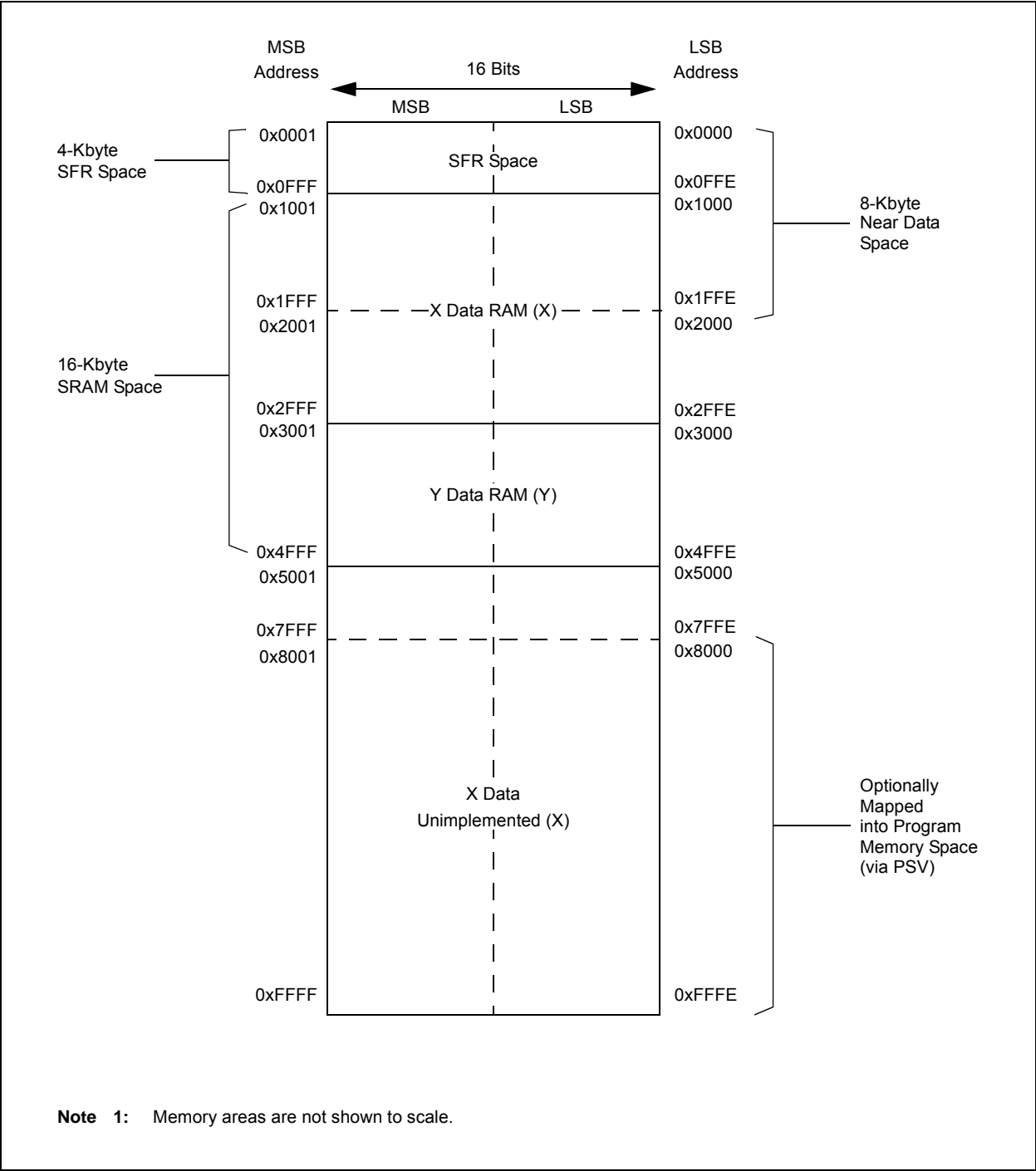
Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPS
Connectivity	CANbus, I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 11x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev256gm102-e-sp

dsPIC33EVXXG M00X/10X FAMILY

FIGURE 4-8: DATA MEMORY MAP FOR 256-Kbyte DEVICES⁽¹⁾



4.3.3 DATA MEMORY ARBITRATION AND BUS MASTER PRIORITY

EDS accesses from bus masters in the system are arbitrated.

The arbiter for data memory (including EDS) arbitrates between the CPU, the DMA and the MPLAB® ICD module. In the event of coincidental access to a bus by the bus masters, the arbiter determines which bus master access has the highest priority. The other bus masters are suspended and processed after the access of the bus by the bus master with the highest priority.

By default, the CPU is Bus Master 0 (M0) with the highest priority and the MPLAB ICD is Bus Master 4 (M4) with the lowest priority. The remaining bus master (DMA Controller) is allocated to M3 (M1 and M2 are reserved and cannot be used). The user application may raise or lower the priority of the DMA Controller to be above that of the CPU by setting the appropriate bits in the EDS Bus Master Priority Control (MSTRPR) register. All bus masters with raised priorities will maintain the same priority relationship relative to each other (i.e., M1 being highest and M3 being lowest, with M2 in between). Also, all the bus masters with priorities

below that of the CPU maintain the same priority relationship relative to each other. The priority schemes for bus masters with different MSTRPR values are listed in Table 4-44.

Figure 4-13 shows the arbiter architecture.

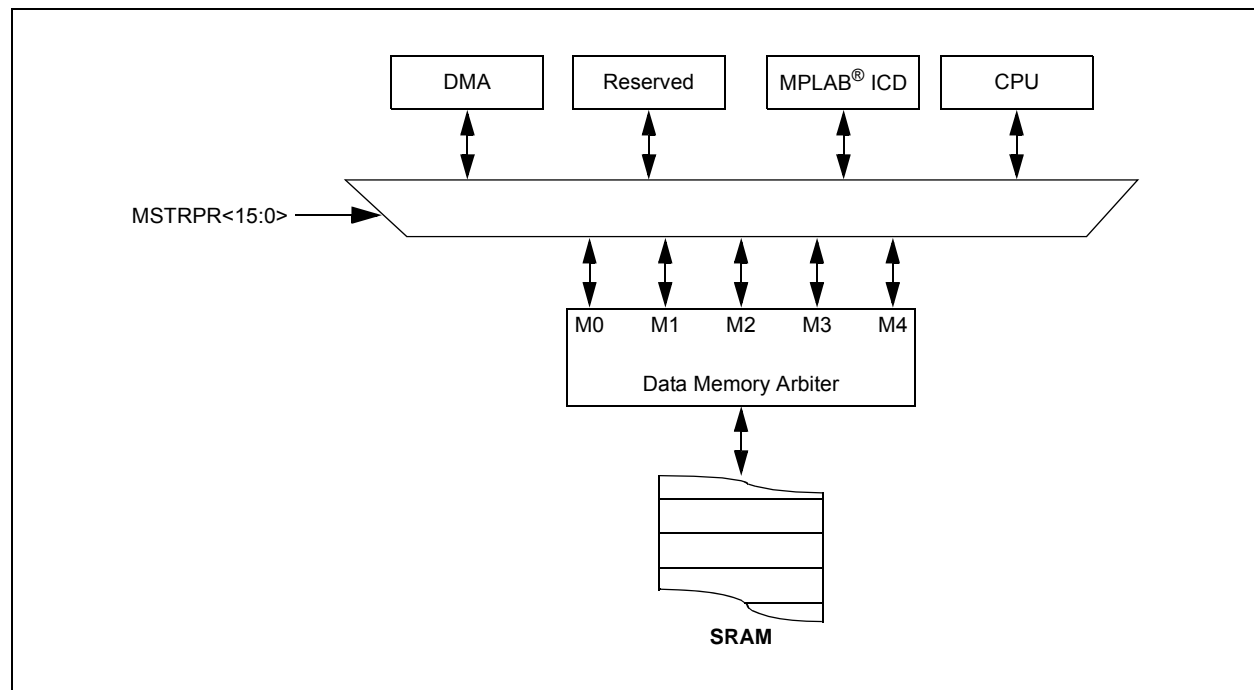
The bus master priority control allows the user application to manipulate the real-time response of the system, either statically during initialization or dynamically in response to real-time events.

TABLE 4-44: DATA MEMORY BUS ARBITER PRIORITY

Priority	MSTRPR<15:0> Bit Setting ⁽¹⁾	
	0x0000	0x0020
M0 (highest)	CPU	DMA
M1	Reserved	CPU
M2	Reserved	Reserved
M3	DMA	Reserved
M4 (lowest)	MPLAB® ICD	MPLAB ICD

Note 1: All other values of MSTRPR<15:0> are reserved.

FIGURE 4-13: ARBITER ARCHITECTURE



6.0 RESETS

Note 1: This data sheet summarizes the features of the dsPIC33EVXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “Reset” (DS70602) in the “dsPIC33/PIC24 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Reset module combines all Reset sources and controls the device Master Reset Signal, $\overline{\text{SYSRST}}$. The following is a list of device Reset sources:

- POR: Power-on Reset
- BOR: Brown-out Reset
- $\overline{\text{MCLR}}$: Master Clear Pin Reset
- SWR: RESET Instruction
- WDTO: Watchdog Timer Time-out Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Condition Device Reset
 - Illegal Opcode Reset
 - Uninitialized W Register Reset
 - Security Reset
 - Illegal Address Mode Reset

A simplified block diagram of the Reset module is shown in Figure 6-1.

Any active source of Reset will make the $\overline{\text{SYSRST}}$ signal active. On system Reset, some of the registers associated with the CPU and peripherals are forced to a known Reset state and some are unaffected.

Note: Refer to the specific peripheral section or **Section 4.0 “Memory Organization”** of this device data sheet for register Reset states.

All types of device Reset set a corresponding status bit in the RCON register to indicate the type of Reset (see Register 6-1).

A POR clears all the bits, except for the POR and BOR bits ($\text{RCON}<1:0>$) that are set. The user application can set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software does not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in the other sections of this device data sheet.

Note: The status bits in the RCON register should be cleared after they are read. Therefore, the next RCON register value after a device Reset is meaningful.

Note: In all types of Resets, to select the device clock source, the contents of OSCCON are initialized from the FNOSC_x Configuration bits in the FOSCSEL Configuration register.

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REGISTER 8-5: DMAxSTBH: DMA CHANNEL x START ADDRESS REGISTER B (HIGH)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<23:16>							
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-0 **STB<23:16>:** DMA Secondary Start Address bits (source or destination)

REGISTER 8-6: DMAxSTBL: DMA CHANNEL x START ADDRESS REGISTER B (LOW)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<7:0>							
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0 **STB<15:0>:** DMA Secondary Start Address bits (source or destination)

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REGISTER 8-7: DMAxPAD: DMA CHANNEL x PERIPHERAL ADDRESS REGISTER⁽¹⁾

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0 **PAD<15:0>**: DMA Peripheral Address Register bits

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

REGISTER 8-8: DMAxCNT: DMA CHANNEL x TRANSFER COUNT REGISTER⁽¹⁾

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CNT<13:8> ⁽²⁾					
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CNT<7:0> ⁽²⁾							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-0 **CNT<13:0>**: DMA Transfer Count Register bits⁽²⁾

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

2: The number of DMA transfers = CNT<13:0> + 1.

11.0 I/O PORTS

Note 1: This data sheet summarizes the features of the dsPIC33EVXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “I/O Ports” (DS70000598) in the “dsPIC33/PIC24 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

Many of the device pins are shared among the peripherals and the Parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity. All the pins in the device are 5V tolerant pins.

11.1 Parallel I/O (PIO) Ports

Generally, a Parallel I/O port that shares a pin with a peripheral is subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of

the I/O pin. The logic also prevents “loop through”, in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 11-1 illustrates how ports are shared with other peripherals and the associated I/O pin to which they are connected.

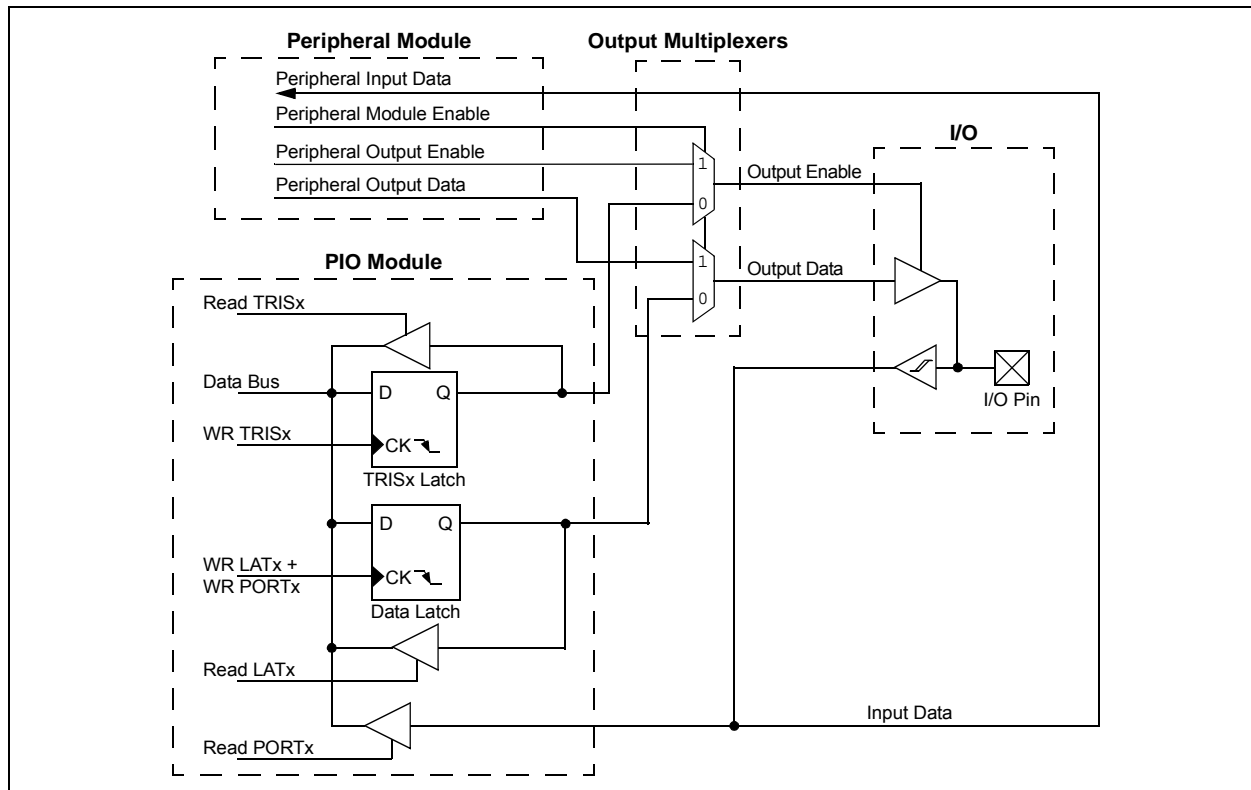
When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin can be read, but the output driver for the parallel port bit is disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin can be driven by a port.

All port pins have eight registers directly associated with their operation as digital I/O. The Data Direction register (TRISx) determines whether the pin is an input or an output. If the Data Direction register bit is a ‘1’, then the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx), read the latch; writes to the latch, write the latch. Reads from the port (PORTx), read the port pins, while writes to the port pins, write the latch.

Any bit and its associated data and control registers that are not valid for a particular device are disabled. This means that the corresponding LATx and TRISx registers, and the port pin are read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port, because there is no other competing source of output.

FIGURE 11-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE



18.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**Serial Peripheral Interface (SPI)**” (DS70005185) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The Serial Peripheral Interface (SPI) module is a synchronous serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, ADC Converters, etc. The SPI module is compatible with the Motorola® SPI and SIOP interfaces.

The dsPIC33EVXXXGM00X/10X device family offers two SPI modules on a single device, SPI1 and SPI2, that are functionally identical. Each SPI module includes an eight-word FIFO buffer and allows DMA bus connections. When using the SPI module with DMA, FIFO operation can be disabled.

Note: In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 and SPI2 modules.

The SPI1 module uses dedicated pins which allow for a higher speed when using SPI1. The SPI2 module takes advantage of the Peripheral Pin Select (PPS) feature to allow for greater flexibility in pin configuration of this module, but results in a lower maximum speed. See **Section 30.0 “Electrical Characteristics”** for more information.

The SPIx serial interface consists of the following four pins:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- SSx/FSYNCx: Active-Low Slave Select or Frame Synchronization I/O Pulse

Note: All of the 4 pins of the SPIx serial interface must be configured as digital in the ANSELx registers.

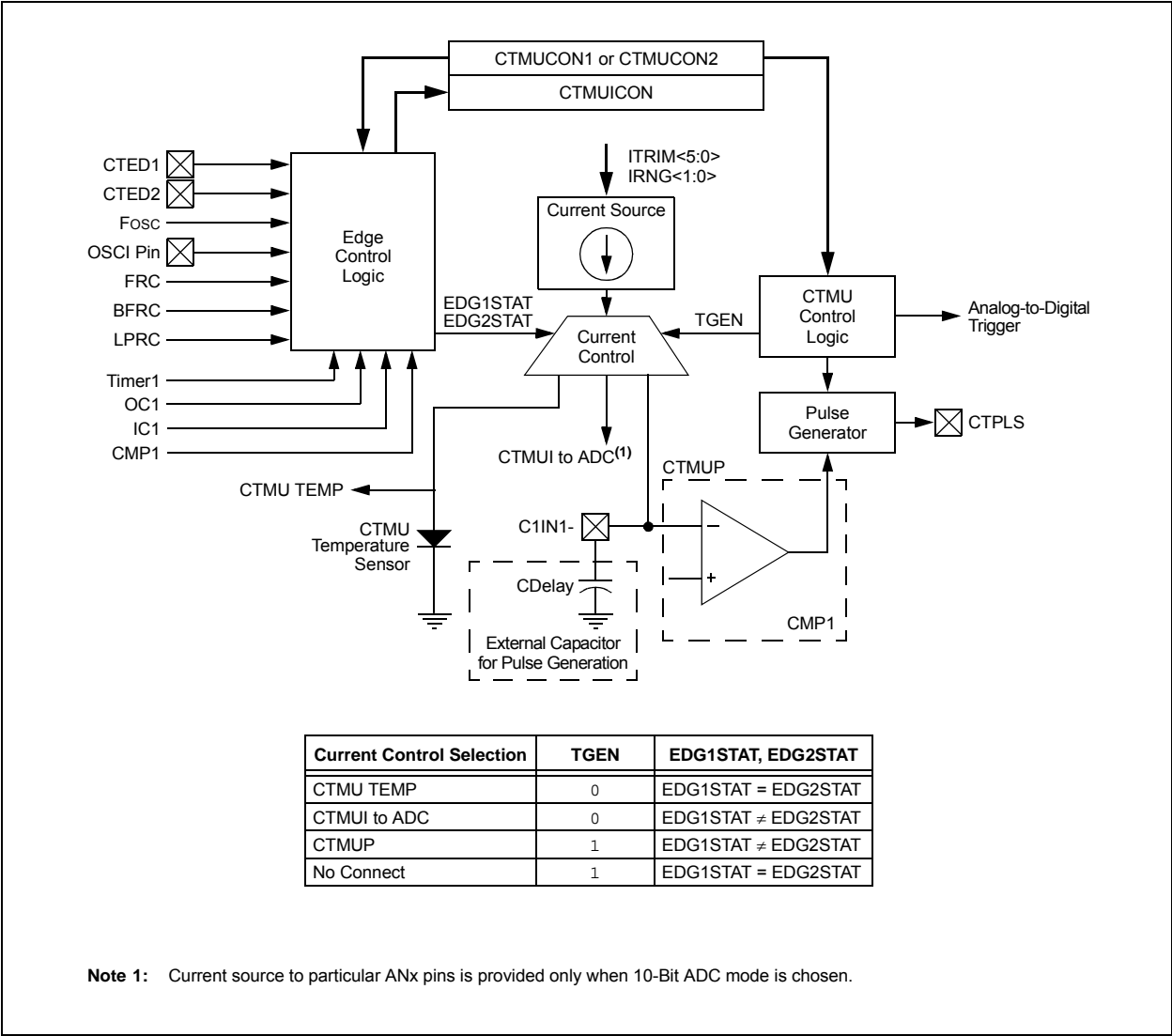
The SPIx module can be configured to operate with two, three or four pins. In 3-pin mode, SSx is not used. In 2-pin mode, neither SDOx nor SSx is used.

Figure 18-1 illustrates the block diagram of the SPIx module in Standard and Enhanced modes.

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NOTES:

FIGURE 23-1: CTMU BLOCK DIAGRAM



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TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
53	MUL	MUL.SS Wb, Ws, Wnd	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		MUL.SS Wb, Ws, Acc	Accumulator = signed(Wb) * signed(Ws)	1	1	None
		MUL.SU Wb, Ws, Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb, Ws, Acc	Accumulator = signed(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb, #lit5, Acc	Accumulator = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.US Wb, Ws, Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.US Wb, Ws, Acc	Accumulator = unsigned(Wb) * signed(Ws)	1	1	None
		MUL.UU Wb, Ws, Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.UU Wb, #lit5, Acc	Accumulator = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb, Ws, Acc	Accumulator = unsigned(Wb) * unsigned(Ws)	1	1	None
		MULW.SS Wb, Ws, Wnd	Wnd = signed(Wb) * signed(Ws)	1	1	None
		MULW.SU Wb, Ws, Wnd	Wnd = signed(Wb) * unsigned(Ws)	1	1	None
		MULW.US Wb, Ws, Wnd	Wnd = unsigned(Wb) * signed(Ws)	1	1	None
		MULW.UU Wb, Ws, Wnd	Wnd = unsigned(Wb) * unsigned(Ws)	1	1	None
		MUL.SU Wb, #lit5, Wnd	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.SU Wb, #lit5, Wnd	Wnd = signed(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb, #lit5, Wnd	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL.UU Wb, #lit5, Wnd	Wnd = unsigned(Wb) * unsigned(lit5)	1	1	None
		MUL f	W3:W2 = f * WREG	1	1	None
54	NEG	NEG Acc	Negate Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
		NEG f	$f = \bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG f, WREG	WREG = $\bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG Ws, Wd	$Wd = \overline{Ws} + 1$	1	1	C,DC,N,OV,Z
55	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
56	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
57	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
58	PWRSAB	PWRSAB #lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
59	RCALL	RCALL Expr	Relative Call	1	4	SFA
		RCALL Wn	Computed Call	1	4	SFA
60	REPEAT	REPEAT #lit15	Repeat Next Instruction lit15 + 1 times	1	1	None
		REPEAT Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
61	RESET	RESET	Software device Reset	1	1	None
62	RETFIE	RETFIE	Return from interrupt	1	6 (5)	SFA

Note: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

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TABLE 30-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.	Typ. ⁽²⁾	Max.	Units	Conditions		
Operating Current (IDD) ⁽¹⁾						
DC20d	4.5	5.5	mA	-40°C	5.0V	10 MIPS
DC20a	4.65	5.6	mA	+25°C		
DC20b	4.85	6.0	mA	+85°C		
DC20c	5.6	7.2	mA	+125°C		
DC22d	8.6	10.6	mA	-40°C	5.0V	20 MIPS
DC22a	8.8	10.8	mA	+25°C		
DC22b	9.1	11.1	mA	+85°C		
DC22c	9.8	12.6	mA	+125°C		
DC23d	16.8	18.5	mA	-40°C	5.0V	40 MIPS
DC23a	17.2	19.0	mA	+25°C		
DC23b	17.55	19.2	mA	+85°C		
DC23c	18.3	21.0	mA	+125°C		
DC24d	25.15	28.0	mA	-40°C	5.0V	60 MIPS
DC24a	25.5	28.0	mA	+25°C		
DC24b	25.5	28.0	mA	+85°C		
DC24c	25.55	28.5	mA	+125°C		
DC25d	29.0	31.0	mA	-40°C	5.0V	70 MIPS
DC25a	28.5	31.0	mA	+25°C		
DC25b	28.3	31.0	mA	+85°C		

Note 1: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as outputs and driving low
- $\overline{\text{MCLR}} = V_{DD}$, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating or being clocked (defined PMDx bits are all ones)
- CPU executing

```
while(1)
{
  NOP( );
}
```

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

dsPIC33EVXXXGM00X/10X FAMILY

TABLE 30-24: TIMER2 AND TIMER4 (TYPE B TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾		Min.	Typ.	Max.	Units	Conditions
TB10	TtxH	TxCK High Time	Synchronous mode	Greater of: 20 or (Tcy + 20)/N	—	—	ns	Must also meet Parameter TB15, N = Prescaler Value (1, 8, 64, 256)
TB11	TtxL	TxCK Low Time	Synchronous mode	Greater of: 20 or (Tcy + 20)/N	—	—	ns	Must also meet Parameter TB15, N = Prescaler Value (1, 8, 64, 256)
TB15	TtxP	TxCK Input Period	Synchronous mode	Greater of: 40 or (2 Tcy + 40)/N	—	—	ns	N = Prescaler Value (1, 8, 64, 256)
TB20	TCKEXT-MRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 Tcy + 40	—	1.75 Tcy + 40	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 30-25: TIMER3 AND TIMER5 (TYPE C TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾		Min.	Typ.	Max.	Units	Conditions
TC10	TtxH	TxCK High Time	Synchronous	Tcy + 20	—	—	ns	Must also meet Parameter TC15
TC11	TtxL	TxCK Low Time	Synchronous	Tcy + 20	—	—	ns	Must also meet Parameter TC15
TC15	TtxP	TxCK Input Period	Synchronous, with Prescaler	2 Tcy + 40	—	—	ns	N = Prescaler Value (1, 8, 64, 256)
TC20	TCKEXT-MRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 Tcy + 40	—	1.75 Tcy + 40	ns	

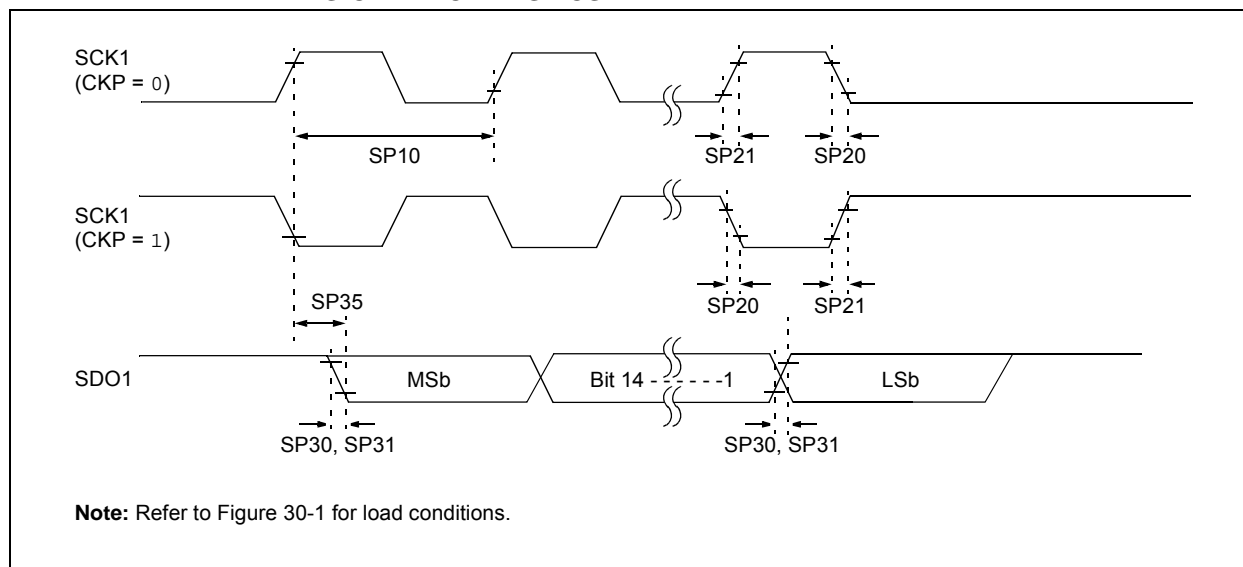
Note 1: These parameters are characterized but not tested in manufacturing.

dsPIC33EVXXXGM00X/10X FAMILY

TABLE 30-38: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS				Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended		
Maximum Data Rate	Master Transmit Only (Half-Duplex)	Master Transmit/Receive (Full-Duplex)	Slave Transmit/Receive (Full-Duplex)	CKE	CKP	SMP
25 MHz	Table 30-39	—	—	0,1	0,1	0,1
25 MHz	—	Table 30-40	—	1	0,1	1
25 MHz	—	Table 30-41	—	0	0,1	1
25 MHz	—	—	Table 30-42	1	0	0
25 MHz	—	—	Table 30-43	1	1	0
25 MHz	—	—	Table 30-44	0	1	0
25 MHz	—	—	Table 30-45	0	0	0

FIGURE 30-20: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



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TABLE 31-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$ for High Temperature				
Param No.	Symbol	Characteristic	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
DI10	V _{IL}	Input Low Voltage Any I/O Pins	V _{SS}	—	0.2 V _{DD}	V	
DI20	V _{IH}	Input High Voltage I/O Pins	0.75 V _{DD}	—	5.5	V	
DI30	ICNPU	Change Notification Pull-up Current	200	375	600	μA	V _{DD} = 5.0V, V _{PIN} = V _{SS}
DI31	ICNPD	Change Notification Pull-Down Current⁽⁷⁾	175	400	625	μA	V _{DD} = 5.0V, V _{PIN} = V _{DD}
DI50	I _{IL}	Input Leakage Current^(2,3) I/O Pins	-200	—	200	nA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at high-impedance
DI55		$\overline{\text{MCLR}}$	-1.5	—	1.5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
DI56		OSC1	-300	—	300	nA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT and HS modes
DI60a	I _{ICL}	Input Low Injection Current	0	—	-5 ^(4,6)	mA	All pins except V _{DD} , V _{SS} , AV _{DD} , AV _{SS} , $\overline{\text{MCLR}}$, V _{CAP} and RB7
DI60b	I _{ICH}	Input High Injection Current	0	—	+5 ^(5,6)	mA	All pins except V _{DD} , V _{SS} , AV _{DD} , AV _{SS} , $\overline{\text{MCLR}}$, V _{CAP} , RB7 and all 5V tolerant pins ⁽⁵⁾
DI60c	ΣI _{ICT}	Total Input Injection Current (sum of all I/O and control pins)	-20 ⁽⁷⁾	—	+20 ⁽⁷⁾	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (I _{ICL} + I _{ICH}) ≤ ΣI _{ICT}

Note 1: Data in “Typ.” column is at 5.0V, +25°C unless otherwise stated.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

5: Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.

6: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

7: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted, provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

dsPIC33EVXXXGM00X/10X FAMILY

FIGURE 33-7: TYPICAL I_{IDLE} vs. V_{DD} (EC MODE, 20 MIPS)

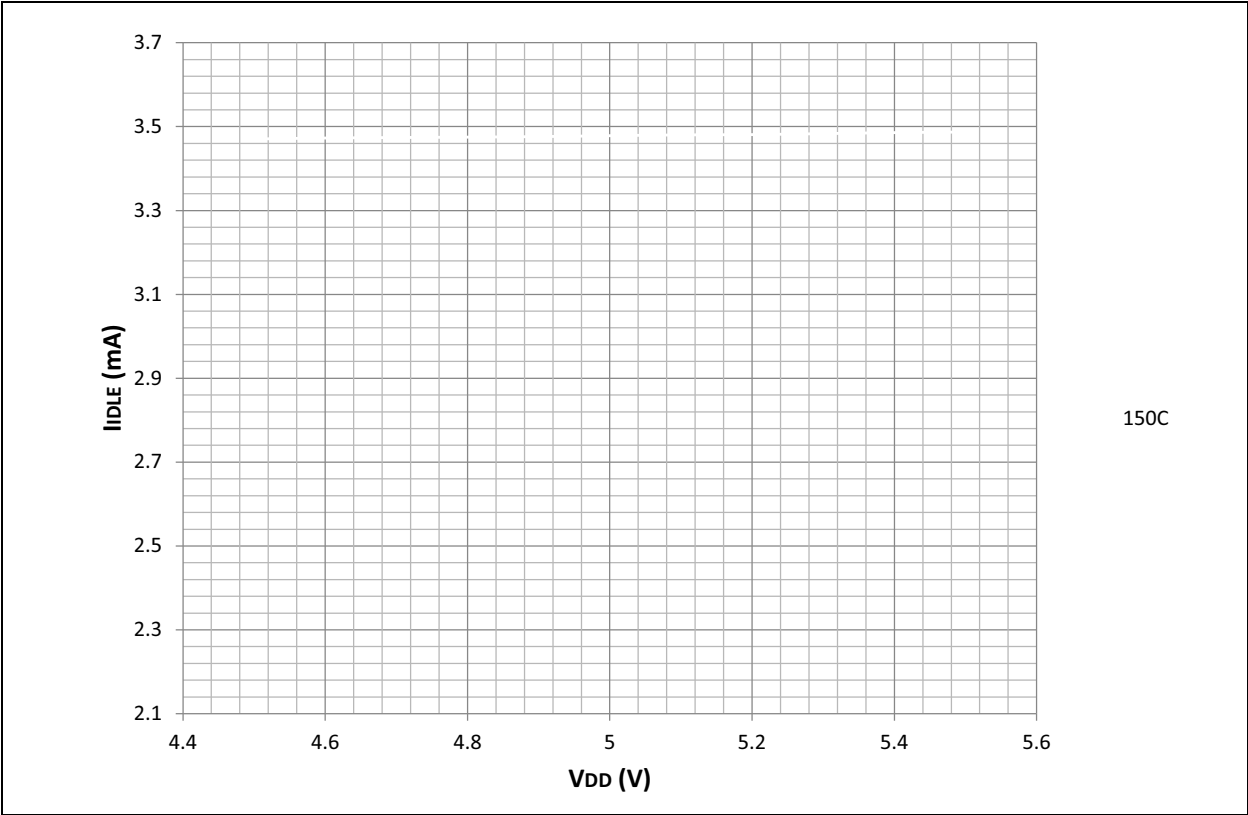
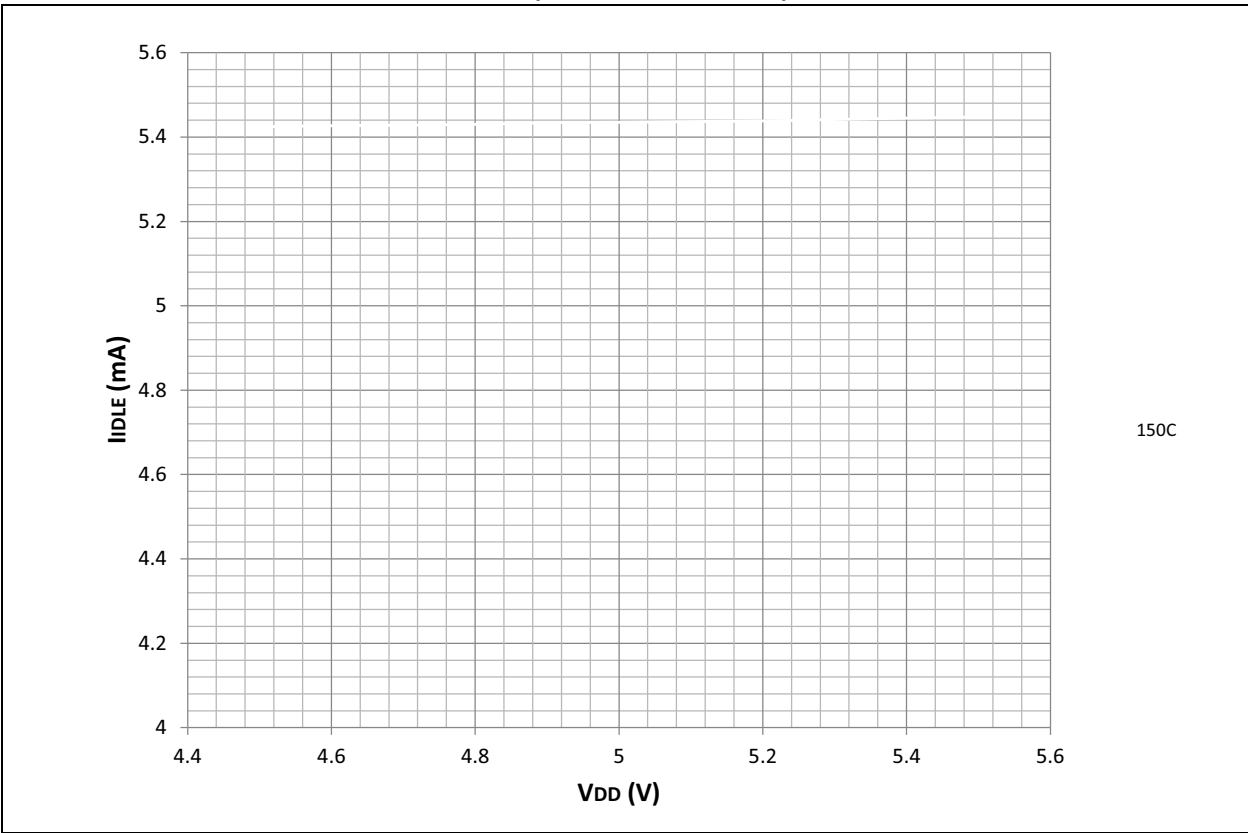


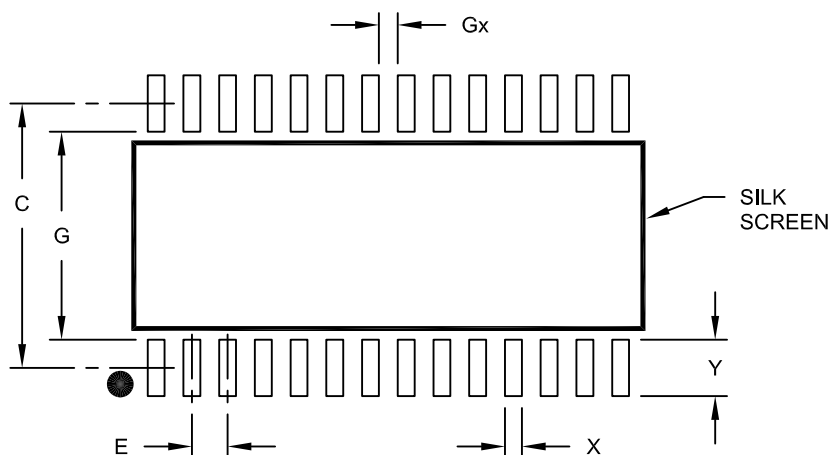
FIGURE 33-8: TYPICAL I_{IDLE} vs. V_{DD} (EC MODE, 40 MIPS)



dsPIC33EVXXXGM00X/10X FAMILY

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

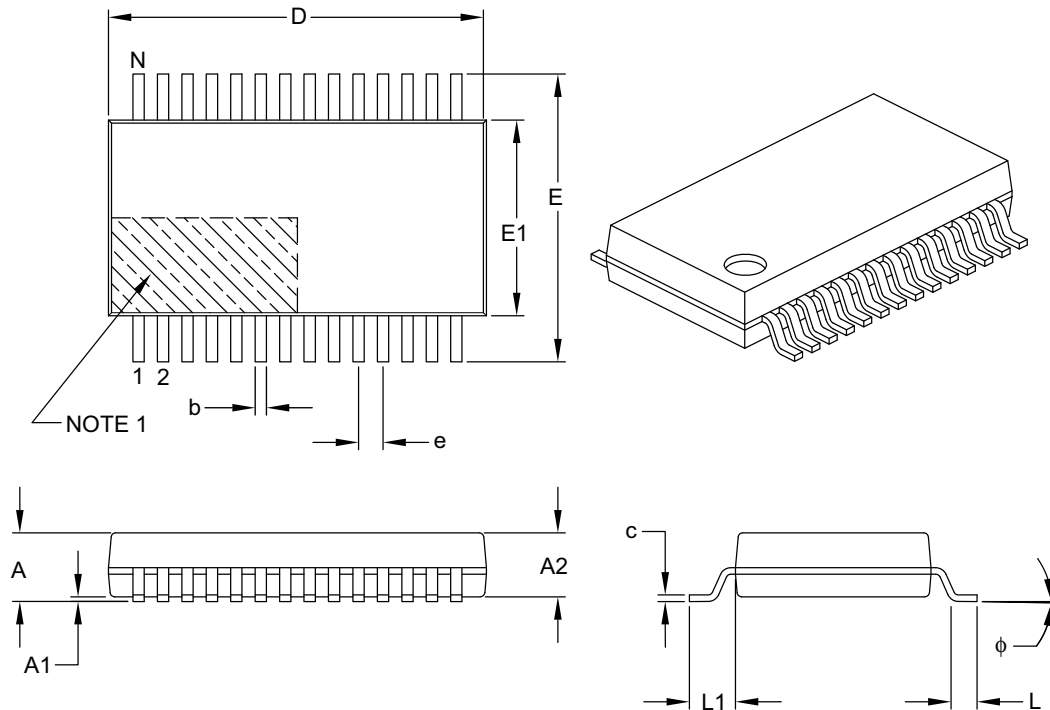
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

dsPIC33EVXXXGM00X/10X FAMILY

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

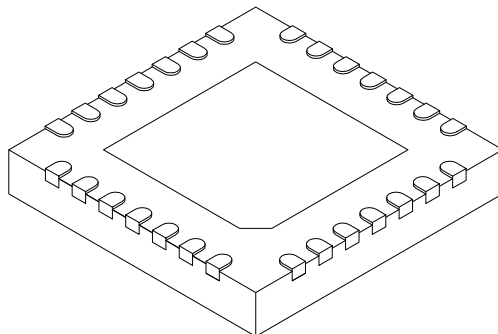
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

dsPIC33EVXXXGM00X/10X FAMILY

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S] With 0.40 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.20 REF		
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	3.65	3.70	4.70
Overall Length	D	6.00 BSC		
Exposed Pad Length	D2	3.65	3.70	4.70
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

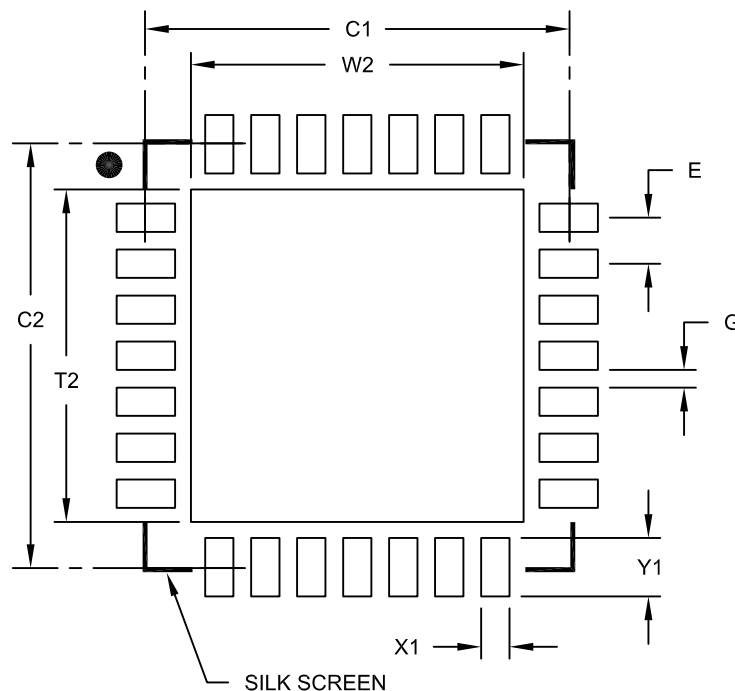
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-124C Sheet 2 of 2

dsPIC33EVXXXGM00X/10X FAMILY

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

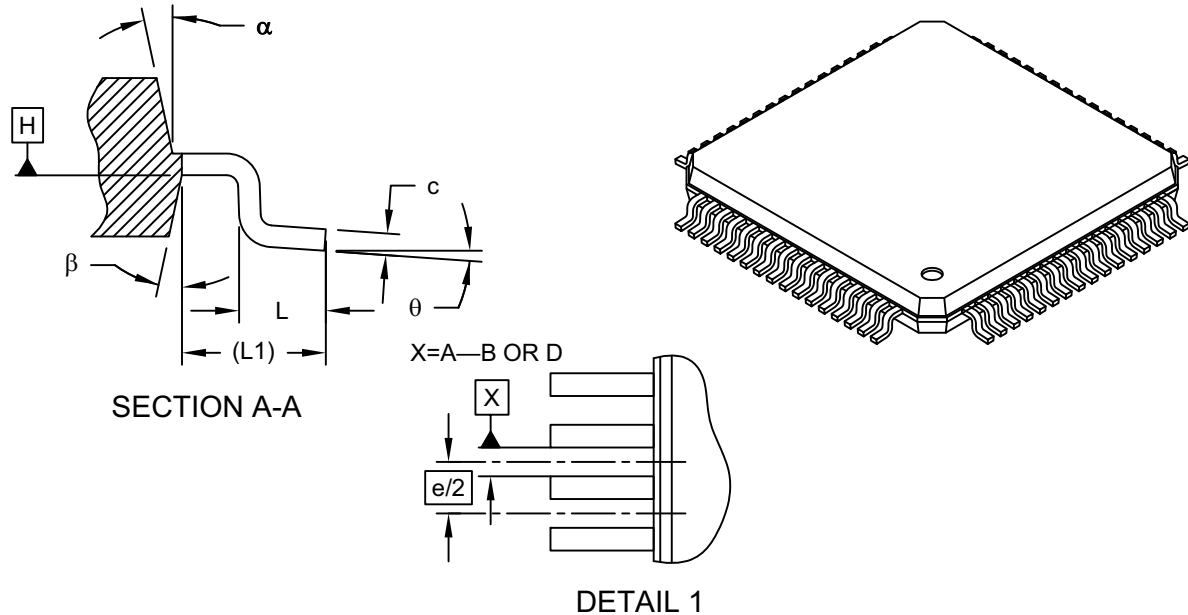
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

dsPIC33EVXXXGM00X/10X FAMILY

64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.50 BSC		
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085C Sheet 2 of 2